

Code :RR320405

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III B.Tech II Semester(RR) Supplementary Examinations, April/May 2011

VLSI DESIGN
(Electronics & Communication Engineering)

Time: 3 hours

Max Marks: 80

Answer any FIVE questions
All questions carry equal marks

- (a) With neat sketches explain the Drain characteristics of the p-channel Enhancement MOS-FET.
(b) An p-MOS Transistor is operated in the Active region with the following parameters $V_{GS} = -4.5V$; $V_{tp} = -1V$; $W/L = 95$; $\mu_n C_{ox} = 95 \mu A/V^2$
Find its drain current and drain source resistance.
- With neat sketches explain how pnp transistor is fabricated in Bipolar process.
- Design a stick diagram for n-MOS Ex-OR gate.
- Design a layout diagram for the NMOS logic shown below $Y = \overline{(A + B + C)}$
- Calculate on resistance of the circuit shown in Figure 1 from V_{DD} to GND. If n-channel sheet resistance $R_{sn} = 10^4 \Omega$ per square and p-channel sheet resistance $R_{sp} = 3.5 \times 10^4 \Omega$ per square. [16]

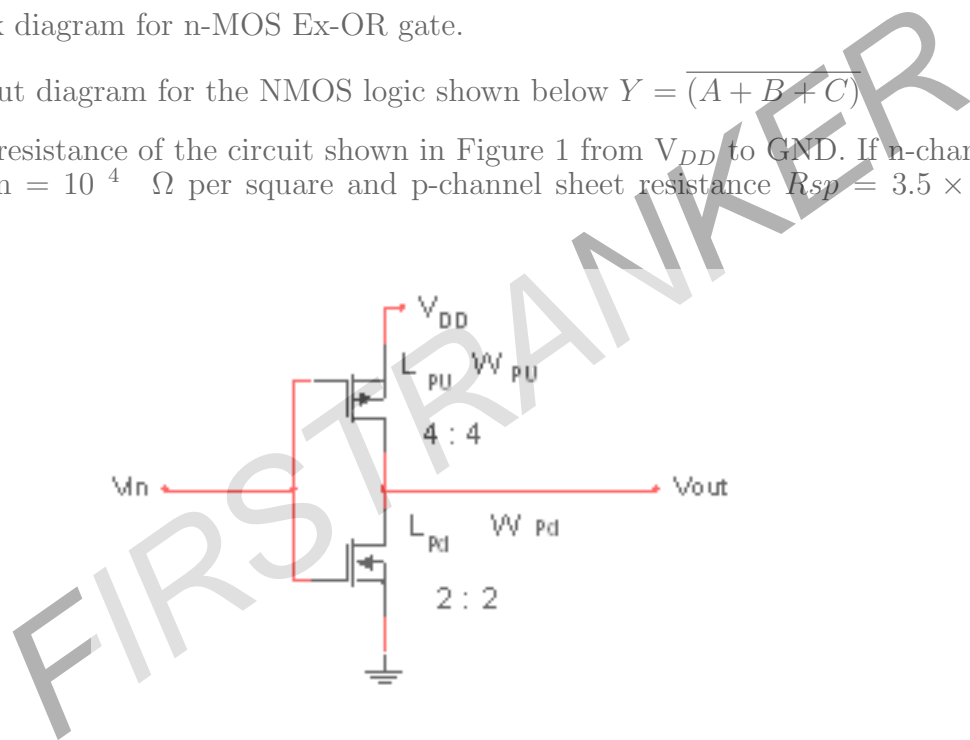


Figure 1:

- Implement 4:1 Multiplexer using PLA.
- What is need for RTL simulation? Clearly explain RTL simulation flow in the ASIC design flow and also mention few leading simulation tools.
- With neat sketches explain the oxidation process in the IC fabrication process.
